

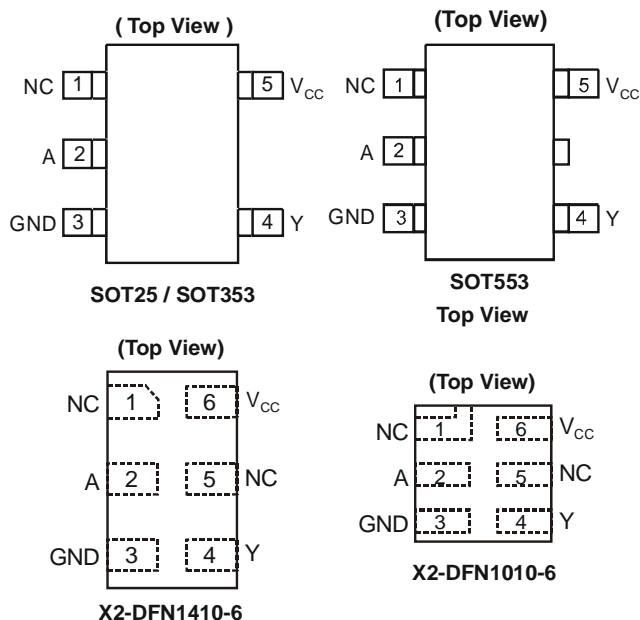
Description

The 74LVC1G06 is a single inverter gate with an open drain output. The device is designed for operation with a power supply range of 1.65V to 5.5V. The input is tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down. The open-drain output can be connected to other open drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32 mA.

Features

- Wide Supply Voltage Range from 1.65 to 5.5V
- 24mA Sink Current at 3.3V
- CMOS low power consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs accept up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 200-V Machine Model (A115-A)
 - Exceeds 2000-V Human Body Model (A114-A)
 - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 100mA per JESD 78, Class II
- Range of Package Options
- All packages Assembled with “Green” Molding Compound (no Br, Sb)
- Lead Free Finish/ RoHS Compliant (Note 1)

Pin Assignments



Applications

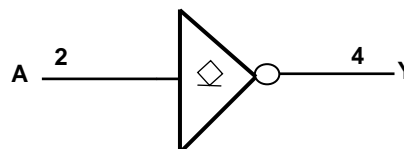
- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of products such as:
 - PCs, networking, notebooks, netbooks, PDAs
 - Tablet Computers, E-readers
 - Computer peripherals, hard drives, CD/DVD ROM
 - TV, DVD, DVR, set top box
 - Cell Phones, Personal Navigation / GPS
 - MP3 players, Cameras, Video Recorders

Notes: 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. No purposely added lead. Halogen and Antimony free. Please visit our website at http://www.diodes.com/products/lead_free.html

Pin Descriptions

Pin Name	Description
NC	No Connection
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage

Logic Diagram



Function Table

Inputs	Output
A	Y
H	L
L	Z

Absolute Maximum Ratings (Note 3)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage applied to output in high impedance or I _{OFF} state	-0.5 to 6.5	V
V _O	Voltage applied to output in high or low state	-0.3 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous output current	50	mA
I _{CC} , I _{GND}	Continuous current through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to 150	°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes: 2. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 3)

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data retention only	1.5		V
V _{IH}	High-level Input Voltage	V _{CC} = 1.65V to 1.95V	0.65 X V _{CC}		V
		V _{CC} = 2.3V to 2.7V	1.7		
		V _{CC} = 3V to 3.6V	2		
		V _{CC} = 4.5V to 5.5V	0.7 X V _{CC}		
V _{IL}	Low-level input voltage	V _{CC} = 1.65V to 1.95V		0.35 X V _{CC}	V
		V _{CC} = 2.3V to 2.7V		0.7	
		V _{CC} = 3V to 3.6V		0.8	
		V _{CC} = 4.5V to 5.5V		0.3 X V _{CC}	
V _I	Input Voltage	0	5.5	V	
V _O	Output Voltage	0	V _{CC}	V	
I _{OL}	Low-level output current	V _{CC} = 1.65V		4	mA
		V _{CC} = 2.3V		8	
		V _{CC} = 3V		16	
				24	
V _{CC} = 4.5V		32			
Δt/ΔV	Input transition rise or fall rate	V _{CC} = 1.8V ± 0.15V, 2.5V ± 0.2V		20	ns/V
		V _{CC} = 3.3V ± 0.3V		10	
		V _{CC} = 5V ± 0.5V		5	
T _A	Operating free-air temperature	-40	125	°C	

Notes: 3. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	-40°C to 85°C			-40°C to 125°C		Unit
				Min	Typ.	Max	Min	Max	
V_{OL}	Low Level Output Voltage	$I_{OL} = 100\mu A$	1.65V to 5.5V			0.1		0.1	V
		$I_{OL} = 4mA$	1.65V			0.45		0.7	
		$I_{OL} = 8mA$	2.3V			0.3		0.45	
		$I_{OL} = 16mA$	3V			0.4		0.6	
		$I_{OL} = 24mA$				0.55		0.8	
		$I_{OL} = 32mA$	4.5V			0.55		.8	
I_I	Input Current	$V_I = 5.5V$ or GND	0 to 5.5V		± 0.1	± 5		± 100	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5V$	0V			± 10		± 200	μA
I_{CC}	Supply Current	$V_I = 5.5V$ or GND $I_O = 0$	5.5V		0.1	10		200	μA
ΔI_{CC}	Additional Supply Current	Input at $V_{CC} - 0.6V$	3V to 5.5V			500		5000	μA
C_i	Input Capacitance	$V_i = V_{CC}$ – or GND	3.3V		5				pF

Package Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = 25^\circ C$)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ.	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 4)		204		$^\circ C/W$
		SOT353			371		
		SOT553			231		
		X2-DFN1010-6			445		
		X2-DFN1410-6			460		
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 4)		52		$^\circ C/W$
		SOT353			143		
		SOT553			105		
		X2-DFN1010-6			250		
		X2-DFN1410-6			265		

Notes: 4. Test condition for SOT25, SOT353, SOT553, X2-DFN1410-6 and X2-DFN1010-6: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

Figure 1 Typical Values at $T_A = 25^\circ C$ and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V.

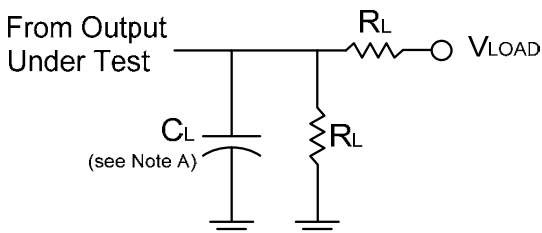
Parameter	From Input	To Output	V_{CC}	$T_A = -40^\circ C$ to $85^\circ C$			$T_A = -40^\circ C$ to $125^\circ C$		Unit
				Min	Typ	Max	Min	Max	
t_{pd}	A or B	Y	$1.8V \pm 0.15V$	1.0	3.0	6.5	1.0	8.5	ns
			$2.5V \pm 0.2V$	0.5	1.9	4.0	0.5	5.5	
			2.7V	0.5	2.5	4.5	0.5	6.0	
			$3.3V \pm 0.3V$	0.5	2.3	4.0	0.5	5.5	
			$5.0V \pm 0.5V$	0.5	1.7	3.0	0.5	4.0	

Operating Characteristics

$T_A = 25^\circ C$

Parameter	Test Conditions	$V_{CC} = 1.8V$	$V_{CC} = 2.5V$	$V_{CC} = 3.3V$	$V_{CC} = 5V$	Unit	
		Typ.	Typ.	Typ.	Typ.		
C_{pd}	Power dissipation capacitance	$f = 10\text{ MHz}$	3	3	4	6	pF

Parameter Measurement Information



TEST	Condition
t_{PLZ} (see Notes D and E)	Vload
t_{PZL} (see Notes D and F)	Vload

V_{CC}	Inputs		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8V \pm 0.15V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	1K Ω	0.15V
$2.5V \pm 0.2V$	V_{CC}	$\leq 2ns$	$V_{CC}/2$	$2 \times V_{CC}$	30pF	500 Ω	0.15V
2.7V	2.7V	$\leq 2.5ns$	1.5V	6V	50pF	500 Ω	0.3V
$3.3V \pm 0.3V$	3V	$\leq 2.5ns$	1.5V	6V	50pF	500 Ω	0.3V
$5V \pm 0.5V$	V_{CC}	$\leq 2.5ns$	$V_{CC}/2$	$2 \times V_{CC}$	50pF	500 Ω	0.3V

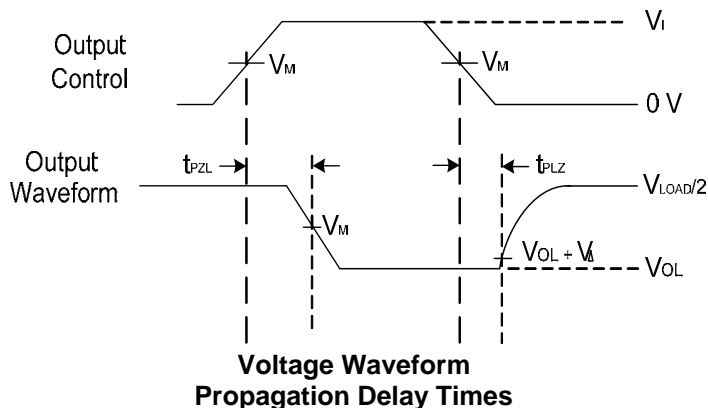
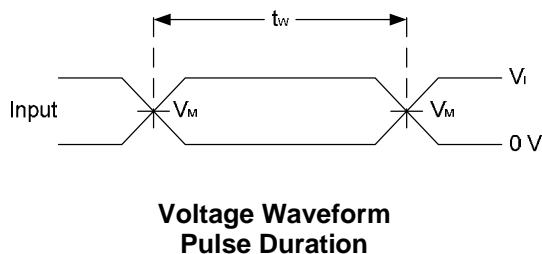
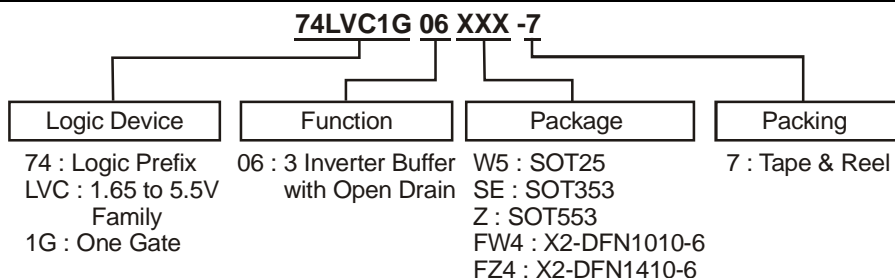


Figure 1. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
 - C. The inputs are measured one at a time with one transition per measurement.
 - D. For the open drain device t_{PLZ} and t_{PZL} are the same as t_{PD}
 - E. t_{PZL} is measured at V_M .
 - F. t_{PLZ} is measured at $V_{OL} + V_{\Delta}$

Ordering Information

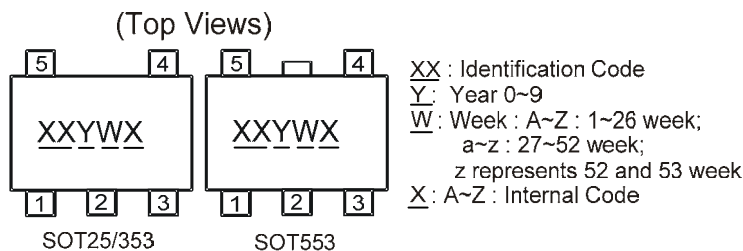


Device	Package Code	Packaging (Note 6)	7" Tape and Reel	
			Quantity	Part Number Suffix
74LVC1G06W5-7	W5	SOT25	3000/Tape & Reel	-7
74LVC1G06SE-7	SE	SOT353	3000/Tape & Reel	-7
74LVC1G06Z-7	Z	SOT553	4000/Tape & Reel	-7
74LVC1G06FW4-7	FW4	X2-DFN1010-6	5000/Tape & Reel	-7
74LVC1G06FZ4-7	FZ4	X2-DFN1410-6	5000/Tape & Reel	-7

Notes: 5. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>
 6. The taping orientation is located on our website at <http://www.diodes.com/datasheets/ap02007.pdf>

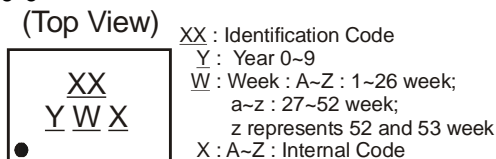
Marking Information

(1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G06W5	SOT25	UM
74LVC1G06SE	SOT353	UM
74LVC1G06Z	SOT553	UM

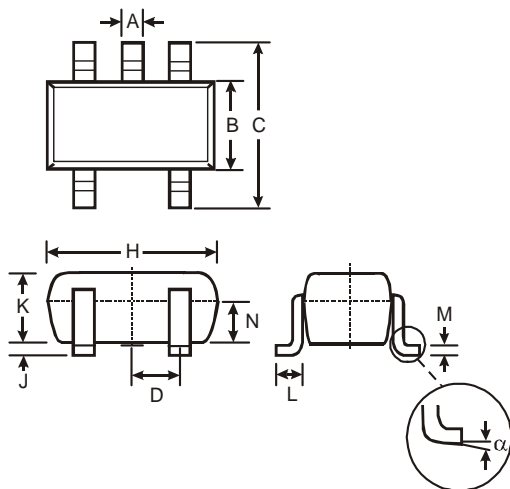
(2) X2-DFN1010-6 and X2-DFN1410-6



Part Number	Package	Identification Code
74LVC1G06FW4	X2-DFN1010-6	UM
74LVC1G06FZ4	X2-DFN1410-6	UM

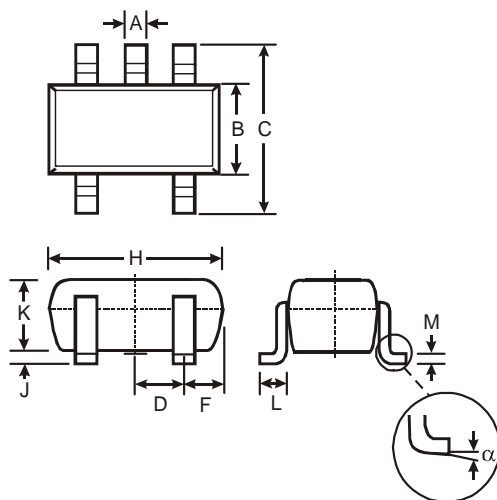
Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



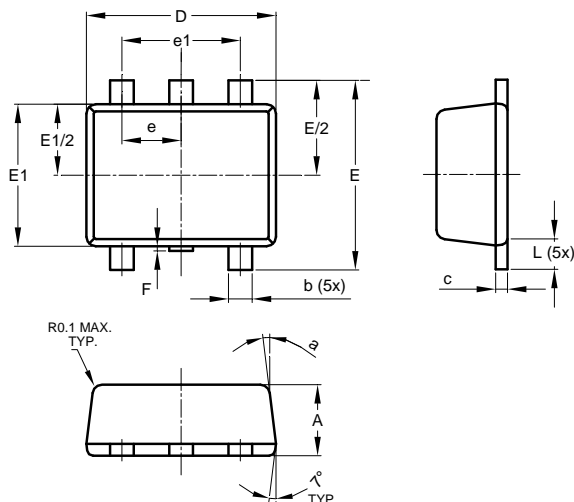
SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	—
All Dimensions in mm			

(2) Package Type: SOT353



SOT353		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

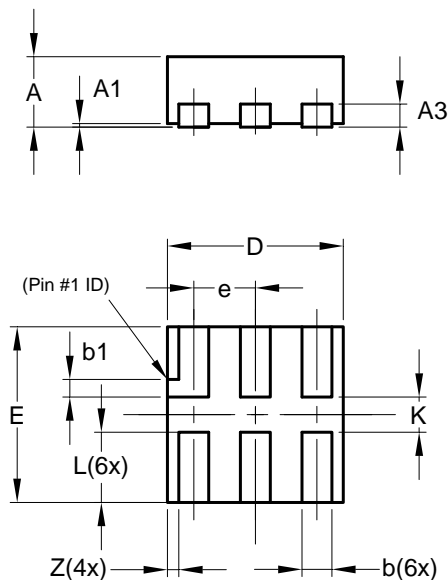
(3) Package Type: SOT553



SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
α	6°	8°	7°
All Dimensions in mm			

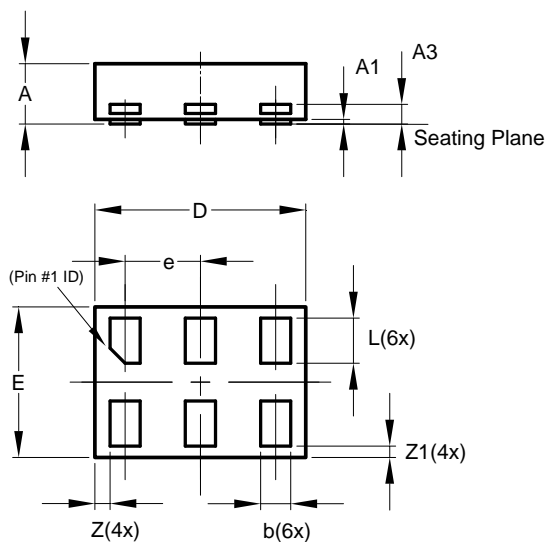
Package Outline Dimensions (cont.)

(4) Package Type X2-DFN1010-6



X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

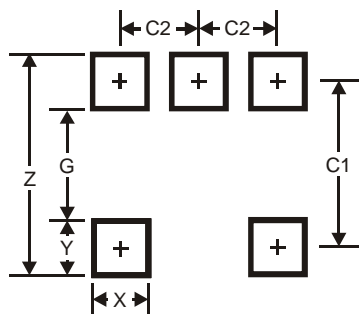
(5) Package Type: X2-DFN1410-6



X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

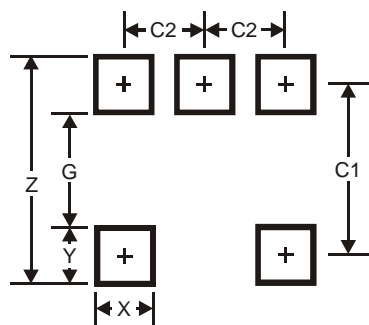
Suggested Pad Layout

(1) Package Type: SOT25



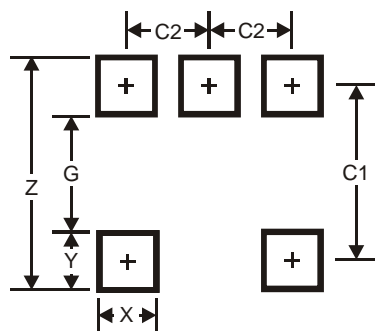
Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: SOT353



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

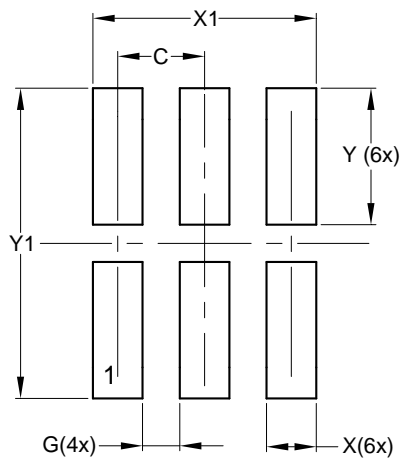
(3) Package Type: SOT553



Dimensions	Value (in mm)
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

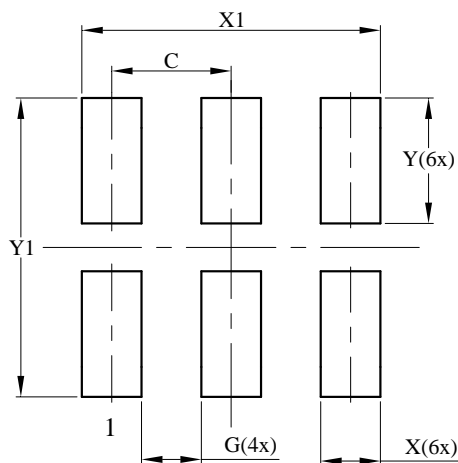
Suggested Pad Layout (cont.)

(4) Package Type X2-DFN1010-6



Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

(5) Package Type: X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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